

Appl. No. 10/821,715
Amdt. dated January 23, 2008
Reply to Office Action of October 23, 2007

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Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1-25. (Canceled)

26. (Currently Amended) A method of making electrical connections between ~~at least one a~~ first electronic component and a second electronic component, comprising:

fabricating a plurality of spring contact elements directly upon ~~said at least one the~~ first electronic component, ~~said the~~ spring contact elements each having a tip end which is spaced above a surface of the ~~at least one~~ first electronic component and at least one of ~~said the plurality of~~ spring contact elements being a different size than ~~the others of the plurality of~~ spring contact elements; and

bringing the ~~at least one~~ first electronic component together with a second electronic component so that the tip ends of the spring contact elements are in electrical contact with corresponding terminals on the second electronic component.

27. (Currently amended) The method according to claim 26, wherein:

the ~~at least one~~ first electronic component is ~~at least one an~~ active semiconductor device;
and

the second electronic component is a test substrate; further comprising:

powering up the active semiconductor device while maintaining the tip ends of the spring contacts in electrical contact with the terminals of the second electronic component.

28. (Canceled)

29. (New) The method according to claim 26, wherein the plurality of spring contact elements each have an elongate structure and the at least one of the plurality of spring contact elements has a different length than the others of the plurality of spring contact elements.

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30. (New) The method according to claim 29, wherein the length is measured in a plane substantially parallel to the surface of the first electronic component.
31. (New) The method according to claim 30, wherein the at least one of the plurality of spring contacts elements has substantially the same spring constant as the others of the plurality of spring contact elements.
32. (New) The method according to claim 26, wherein the at least one of the plurality of spring contacts elements has substantially the same spring constant as the others of the plurality of spring contact elements.
33. (New) The method according to claim 26, wherein the plurality of spring contact elements each have a tapered body coupling the tip end to the surface of the first electronic component.
34. (New) The method according to claim 33, further comprising tailoring the taper for each of the plurality of spring contact elements so that the plurality of spring contact elements each have a substantially equal spring constant.
35. (New) The method according to claim 26, wherein:
the fabricating comprises fabricating additional spring contact elements directly upon at least one other first electronic component, the additional spring contact elements each having a tip end which is spaced above a surface of the at least one other first electronic component; and
the bringing comprises bringing the first electronic component and the at least one other first electronic component together with the second electronic component so that the tip ends of the spring contact elements and the tip ends of the additional spring contact elements are in electrical contact with corresponding terminals on the second electronic component.